

TLVx369 Cost-Optimized, 800-nA, 1.8-V, Rail-to-Rail I/O Operational Amplifier with Zero-Crossover Distortion

1 Features

- Cost-Optimized Precision Amplifier *nanoPower*: 800 nA/Ch (Typ)
- Low Offset Voltage: 400 μV (Typ)
- Rail-to-Rail Input and Output
- Zero-Crossover Distortion
- Low Offset Drift: 0.5 $\mu\text{V}/^\circ\text{C}$ (Typ)
- Gain-Bandwidth Product: 12 kHz
- Supply Voltage: 1.8 V to 5.5 V
- *microSize* Packages: SC70-5, VSSOP-8

2 Applications

- Blood Glucose Meters
- Test Equipment
- Low-Power Sensor Signal Conditioning
- Portable Devices

3 Description

The TLV369 family of single and dual operational amplifiers represents a cost-optimized generation of 1.8-V nanopower amplifiers.

With the zero-crossover distortion circuitry, these amplifiers feature high linearity over the full common-mode input range with no crossover distortion, enabling true rail-to-rail input and operating from a 1.8-V to 5.5-V single supply. The family is also compatible with industry-standard nominal voltages of 3.0 V, 3.3 V, and 5.0 V.

The TLV369 (single version) is offered in a 5-pin SC70 package. The TLV2369 (dual version) comes in 8-pin VSSOP and SOIC packages.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|-----------|-------------------|
| TLV369 | SC70 (5) | 2.00 mm x 1.25 mm |
| TLV2369 | VSSOP (8) | 3.00 mm x 3.00 mm |
| | SOIC (8) | 4.90 mm x 3.91 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

TLV369 Family Eliminates Crossover Distortion Across the Full Supply Range

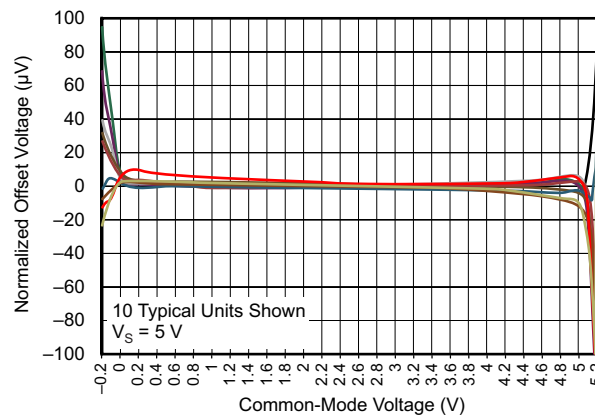


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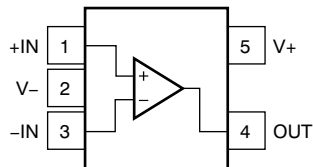
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4 Revision History

| DATE | REVISION | NOTES |
|----------|----------|------------------|
| May 2016 | * | Initial release. |

5 Pin Configuration and Functions

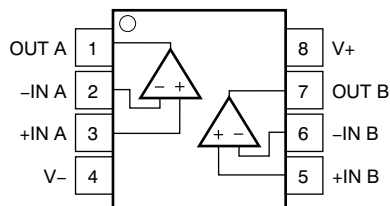
TLV369: DCK Package
5-Pin SC70
Top View



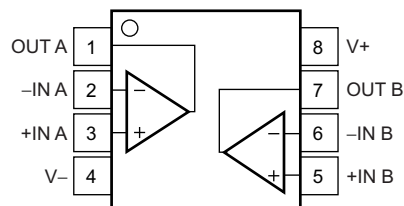
Pin Functions: TLV369

| NAME | PIN | | I/O | DESCRIPTION |
|------|--------|------------|-----|--|
| | TLV369 | DCK (SC70) | | |
| -IN | | 3 | I | Negative (inverting) input |
| +IN | | 1 | I | Positive (noninverting) input |
| OUT | | 4 | O | Output |
| V- | | 2 | — | Negative (lowest) power supply or ground (for single-supply operation) |
| V+ | | 5 | — | Positive (highest) power supply |

TLV2369: D Package
8-Pin SOIC
Top View



TLV2369: DGK Package
8-Pin VSSOP
Top View



Pin Functions: TLV2369

| NAME | PIN | | I/O | DESCRIPTION |
|-------|----------|-------------|-----|---------------------------------|
| | TLV2369 | | | |
| | D (SOIC) | DGK (VSSOP) | | |
| -IN A | 2 | 2 | I | Inverting input, channel A |
| -IN B | 6 | 6 | I | Inverting input, channel B |
| +IN A | 3 | 3 | I | Noninverting input, channel A |
| +IN B | 5 | 5 | I | Noninverting input, channel B |
| OUT A | 1 | 1 | O | Output, channel A |
| OUT B | 7 | 7 | O | Output, channel B |
| V- | 4 | 4 | — | Negative (lowest) power supply |
| V+ | 8 | 8 | — | Positive (highest) power supply |

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|-------------|-------------------------------------|--------------|--------------|------|
| Voltage | Supply, $V_S = (V+) - (V-)$ | 0 | +7 | V |
| | Signal input pin ⁽²⁾ | $(V-) - 0.5$ | $(V+) + 0.5$ | V |
| Current | Signal input pin ⁽²⁾ | -10 | 10 | mA |
| | Output short-circuit ⁽³⁾ | Continuous | | mA |
| Temperature | Operating, T_A | -40 | 125 | °C |
| | Junction, T_J | | 150 | °C |
| | Storage, T_{stg} | -65 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Input pins are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5 V beyond the supply rails must be current limited to 10 mA or less.
- (3) Short-circuit to $V_S / 2$, one amplifier per package.

6.2 ESD Ratings

over operating free-air temperature range (unless otherwise noted).

| | | | VALUE | UNIT |
|-------------|-------------------------|--|-------|------|
| $V_{(ESD)}$ | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾ | ±4000 | V |
| | | Charged device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾ | ±1500 | |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted).

| | | MIN | NOM | MAX | UNIT |
|-------|-----------------------|-----|-----|-----|------|
| V_S | Supply voltage | 1.8 | | 5.5 | V |
| | Specified temperature | -40 | | 85 | °C |

6.4 Thermal Information: TLV369

| THERMAL METRIC ⁽¹⁾ | | TLV369 | | UNIT |
|-------------------------------|--|------------|--|------|
| | | DCK (SC70) | | |
| | | 5 PINS | | |
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 293.3 | | °C/W |
| $R_{\theta JC(top)}$ | Junction-to-case (top) thermal resistance | 95.2 | | °C/W |
| $R_{\theta JB}$ | Junction-to-board thermal resistance | 83.4 | | °C/W |
| ψ_{JT} | Junction-to-top characterization parameter | 2.9 | | °C/W |
| ψ_{JB} | Junction-to-board characterization parameter | 82.4 | | °C/W |
| $R_{\theta JC(bot)}$ | Junction-to-case (bottom) thermal resistance | n/a | | °C/W |

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Thermal Information: TLV2369

| THERMAL METRIC ⁽¹⁾ | | TLV2369 | | UNIT |
|-------------------------------|--|----------|-------------|------|
| | | D (SOIC) | DGK (VSSOP) | |
| | | 8 PINS | 8 PINS | |
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 121.5 | 168.5 | °C/W |
| $R_{\theta JC(top)}$ | Junction-to-case (top) thermal resistance | 66.3 | 58.1 | °C/W |
| $R_{\theta JB}$ | Junction-to-board thermal resistance | 62.5 | 88.9 | °C/W |
| ψ_{JT} | Junction-to-top characterization parameter | 22.8 | 9.3 | °C/W |
| ψ_{JB} | Junction-to-board characterization parameter | 61.9 | 87.6 | °C/W |
| $R_{\theta JC(bot)}$ | Junction-to-case (bottom) thermal resistance | n/a | n/a | °C/W |

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.6 Electrical Characteristics

 V_S (total supply voltage) = 1.8 V to 5.5 V; at $T_A = 25^\circ\text{C}$, and $R_L = 100\text{ k}\Omega$ connected to $V_S / 2$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------------------|--------------------------------|--|-------|-----------------------|-------|------------------------------|
| OFFSET VOLTAGE | | | | | | |
| V_{OS} | Input offset voltage | At $T_A = 25^\circ\text{C}$ | | 0.4 | 2 | mV |
| | | At $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ | | 0.85 | | |
| dV_{OS}/dT | Drift | At $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ | | 0.5 | | $\mu\text{V}/^\circ\text{C}$ |
| PSRR | Power-supply rejection ratio | $V_S = 1.8\text{ V}$ to 5.5 V | 80 | 94 | | dB |
| INPUT VOLTAGE RANGE | | | | | | |
| V_{CM} | Common-mode voltage range | | V_- | | V_+ | V |
| CMRR | Common-mode rejection ratio | $(V_-) \leq V_{CM} \leq (V_+)$ | 80 | 110 | | dB |
| INPUT BIAS CURRENT | | | | | | |
| I_B | Input bias current | At $T_A = 25^\circ\text{C}$ | | 10 | | pA |
| | | At $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ | | See Figure 8 | | |
| I_{OS} | Input offset current | | | 10 | | pA |
| INPUT IMPEDANCE | | | | | | |
| Z_{ID} | Differential | | | $10^{13} \parallel 3$ | | $\Omega \parallel \text{pF}$ |
| Z_{IC} | Common-mode | | | $10^{13} \parallel 6$ | | $\Omega \parallel \text{pF}$ |
| NOISE | | | | | | |
| E_n | Input voltage noise | $f = 0.1\text{ Hz}$ to 10 Hz | | 4 | | μV_{PP} |
| e_n | Input voltage noise density | $f = 1\text{ kHz}$ | | 300 | | $\text{nV}/\sqrt{\text{Hz}}$ |
| i_n | Input current noise density | $f = 1\text{ kHz}$ | | 1 | | $\text{fA}/\sqrt{\text{Hz}}$ |
| OPEN-LOOP GAIN | | | | | | |
| A_{OL} | Open-loop voltage gain | At $V_S = 5.5\text{ V}$, $100\text{ mV} \leq V_O \leq (V_+) - 100\text{ mV}$, $R_L = 100\text{ k}\Omega$ | | 130 | | dB |
| | | At $V_S = 5.5\text{ V}$, $500\text{ mV} \leq V_O \leq (V_+) - 500\text{ mV}$, $R_L = 10\text{ k}\Omega$ | 80 | 120 | | |
| OUTPUT | | | | | | |
| V_O | Voltage output swing from rail | $R_L = 10\text{ k}\Omega$ | | | 25 | mV |
| I_{SC} | Short-circuit current | | | 10 | | mA |
| C_{LOAD} | Capacitive load drive | | | See Figure 10 | | |
| FREQUENCY RESPONSE | | | | | | |
| GBP | Gain bandwidth product | | | 12 | | kHz |
| SR | Slew rate | $G = 1$ | | 0.005 | | $\text{V}/\mu\text{s}$ |
| t_{OR} | Overload recovery time | $V_{IN} \times \text{gain} = V_S$ | | 250 | | μs |
| POWER SUPPLY | | | | | | |
| V_S | Specified voltage range | | 1.8 | | 5.5 | V |
| I_Q | Quiescent current | $I_O = 0\text{ mA}$, at $V_S = 5.5\text{ V}$ | | 800 | 1300 | nA |
| TEMPERATURE | | | | | | |
| | Specified range | | -40 | | 85 | $^\circ\text{C}$ |
| T_A | Operating range | | -40 | | 125 | $^\circ\text{C}$ |

6.7 Typical Characteristics

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, and $R_L = 100\text{ k}\Omega$ connected to $V_S / 2$ (unless otherwise noted)

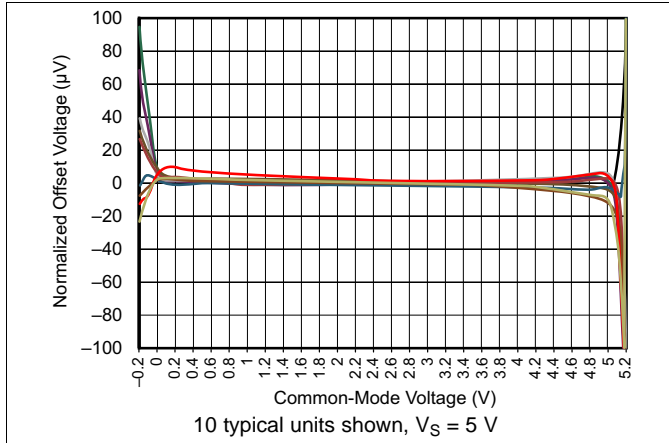


Figure 1. Normalized Offset Voltage vs Common-Mode Voltage

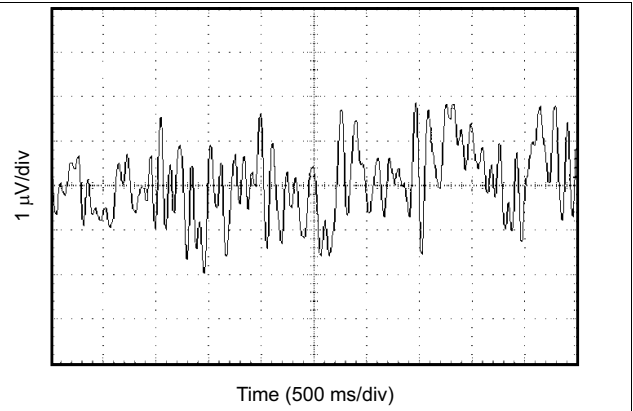


Figure 2. 0.1-Hz to 10-Hz Noise

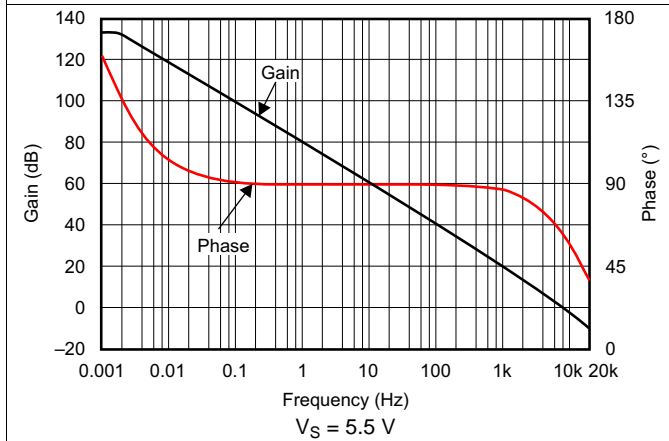


Figure 3. Open-Loop Gain and Phase vs Frequency

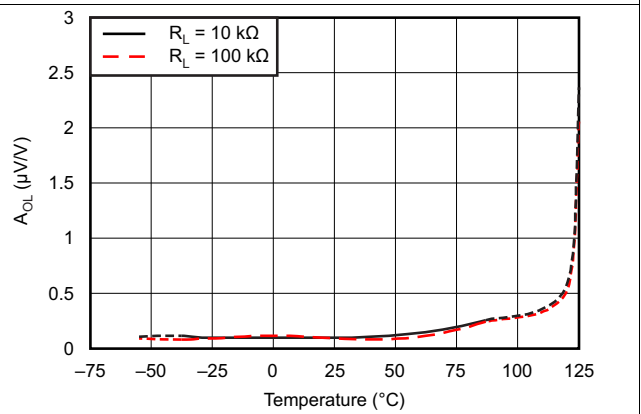


Figure 4. Open-Loop Gain vs Temperature

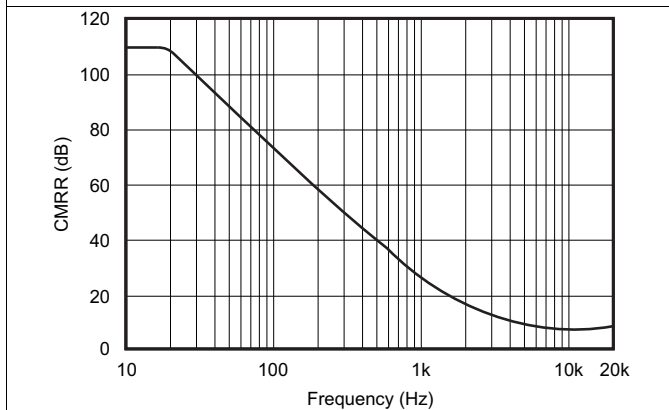


Figure 5. Common-Mode Rejection Ratio vs Frequency

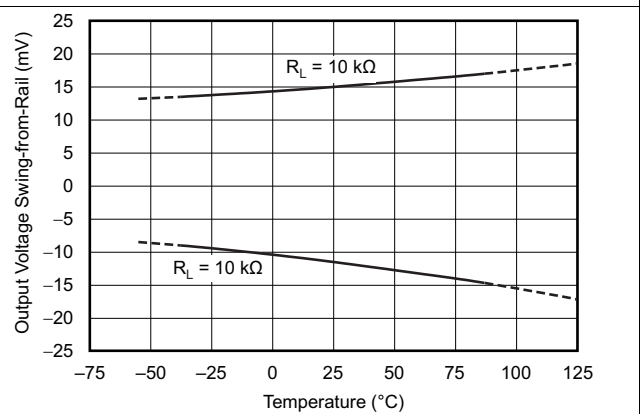
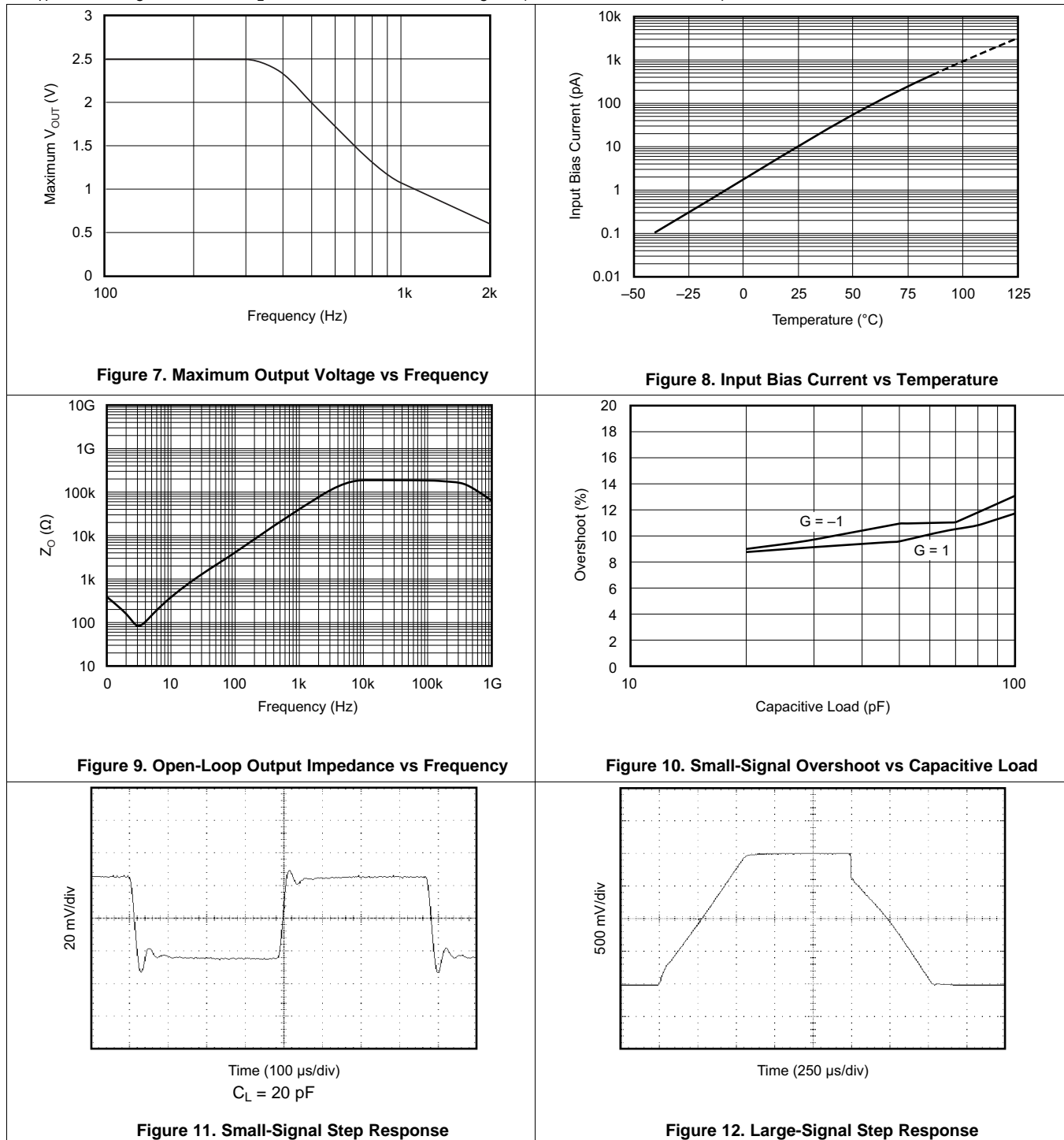


Figure 6. Output Voltage Swing from Rail vs Temperature

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, and $R_L = 100\text{ k}\Omega$ connected to $V_S / 2$ (unless otherwise noted)



Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, and $R_L = 100\text{ k}\Omega$ connected to $V_S / 2$ (unless otherwise noted)

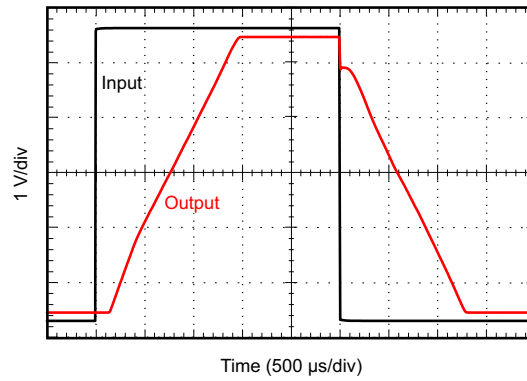


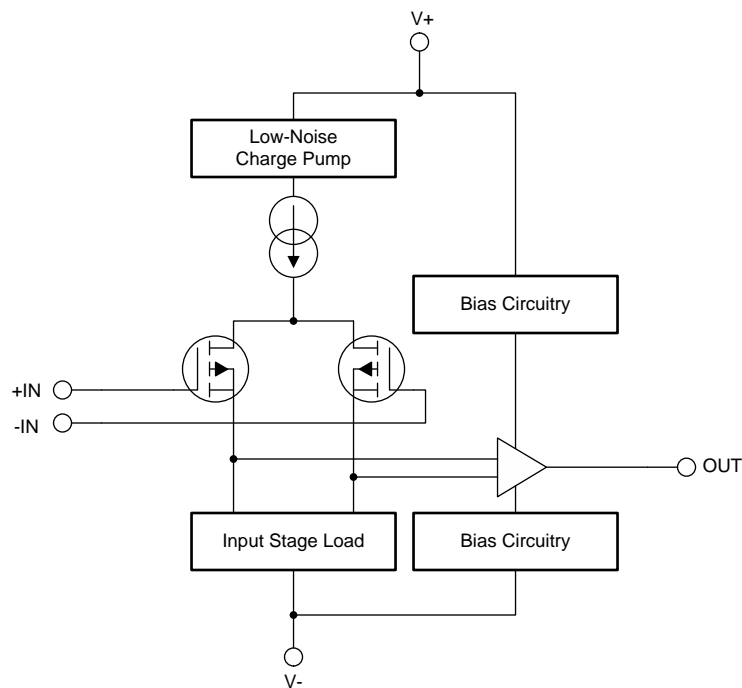
Figure 13. Overload Recovery

7 Detailed Description

7.1 Overview

The TLVx369 family of operational amplifiers minimizes power consumption and operates on supply voltages as low as 1.8 V. The zero-crossover distortion circuitry enables high linearity over the full input common-mode range, achieving true rail-to-rail input from a 1.8-V to 5.5-V single supply.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Operating Voltage

The TLV369 series op amps are fully specified and tested from 1.8 V to 5.5 V (± 0.9 V to ± 2.75 V). Parameters that vary significantly with supply voltage are described in the [Typical Characteristics](#) section.

7.3.2 Input Common-Mode Voltage Range

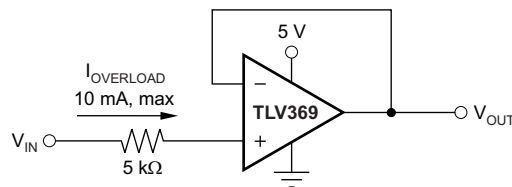
The TLV369 family is designed to eliminate the input offset transition region typically present in most rail-to-rail, complementary-stage operational amplifiers, allowing the TLV369 family of amplifiers to provide superior common-mode performance over the entire input range.

The input common-mode voltage range of the TLV369 family typically extends to each supply rail. CMRR is specified from the negative rail to the positive rail; see [Figure 1](#), *Normalized Offset Voltage vs Common-Mode Voltage*.

7.3.3 Protecting Inputs from Overvoltage

Input currents are typically 10 pA. However, large inputs (greater than 500 mV beyond the supply rails) can cause excessive current to flow in or out of the input pins. Therefore, in addition to keeping the input voltage between the supply rails, the input current must also be limited to less than 10 mA. This limiting is easily accomplished with an input resistor, as shown in [Figure 14](#).

A current-limiting resistor is required if the input voltage exceeds the supply rails by ≥ 0.5 V.



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Figure 14. Input Current Protection for Voltages That Exceed the Supply Voltage

7.4 Device Functional Modes

The TLV369 family has a single functional mode. These devices are powered on as long as the power-supply voltage is between 1.8 V (± 0.9 V) and 5.5 V (± 2.75 V).

8 Application and Implementation

NOTE

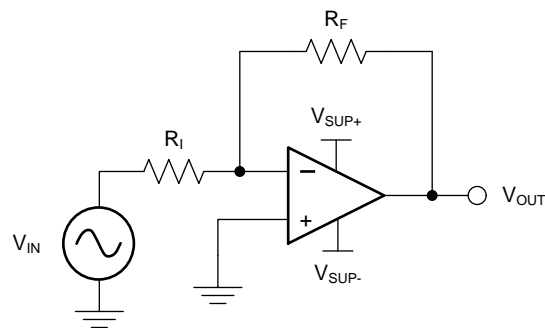
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

When designing for ultra-low power, choose system components carefully. To minimize current consumption, select large-value resistors. Any resistors can react with stray capacitance in the circuit and the input capacitance of the operational amplifier. These parasitic RC combinations can affect the stability of the overall system. Use of a feedback capacitor assures stability and limits overshoot or gain peaking.

8.2 Typical Application

A typical application for an operational amplifier is an inverting amplifier, as shown in [Figure 15](#). An inverting amplifier takes a positive voltage on the input and outputs a signal inverted to the input, making a negative voltage of the same magnitude. In the same manner, the amplifier also makes negative input voltages positive on the output. In addition, amplification can be added by selecting the input resistor R_I and the feedback resistor R_F .



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Figure 15. Application Schematic

8.2.1 Design Requirements

The supply voltage must be chosen to be larger than the input voltage range and the desired output range. The limits of the input common-mode range (V_{CM}) and the output voltage swing to the rails (V_O) must also be considered. For instance, this application scales a signal of ± 0.5 V (1 V) to ± 1.8 V (3.6 V). Setting the supply at ± 2.5 V is sufficient to accommodate this application.

Typical Application (continued)

8.2.2 Detailed Design Procedure

Determine the gain required by the inverting amplifier using [Equation 1](#) and [Equation 2](#):

$$A_V = \frac{V_{OUT}}{V_{IN}} \tag{1}$$

$$A_V = \frac{1.8}{-0.5} = -3.6 \tag{2}$$

When the desired gain is determined, choose a value for R_I or R_F . Choosing a value in the kilohm range is desirable for general-purpose applications because the amplifier circuit uses currents in the milliamp range. This milliamp current range ensures that the device does not draw too much current. The trade-off is that very large resistors (100s of kilohms) draw the smallest current but generate the highest noise. Very small resistors (100s of ohms) generate low noise but draw high current. This example uses 10 k Ω for R_I , meaning 36 k Ω is used for R_F . These values are determined by [Equation 3](#):

$$A_V = -\frac{R_F}{R_I} \tag{3}$$

8.2.3 Application Curve

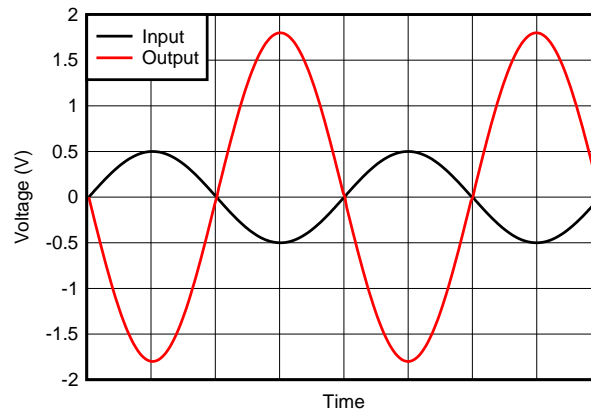
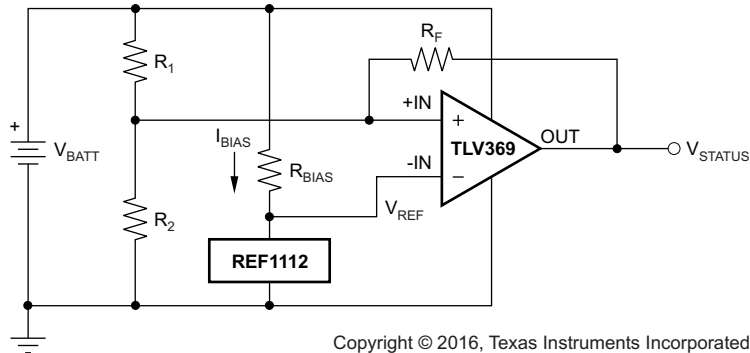


Figure 16. Inverting Amplifier Input and Output

8.3 System Examples

8.3.1 Battery Monitoring

The low operating voltage and quiescent current of the TLV369 series make the family an excellent choice for battery-monitoring applications, as shown in [Figure 17](#).



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Figure 17. Battery Monitor

In this circuit, V_{STATUS} is high as long as the battery voltage remains above 2 V. A low-power reference is used to set the trip point. Resistor values are selected as follows:

1. Selecting R_F : Select R_F such that the current through R_F is approximately 1000 times larger than the maximum bias current over temperature, as given by [Equation 4](#):

$$\begin{aligned} R_F &= \frac{V_{REF}}{1000 (I_{BMAX})} \\ &= \frac{1.2 \text{ V}}{1000 (50 \text{ pA})} \\ &= 24 \text{ M}\Omega \approx 20 \text{ M}\Omega \end{aligned} \tag{4}$$

2. Choose the hysteresis voltage, V_{HYST} . For battery-monitoring applications, 50 mV is adequate.
3. Calculate R_1 as calculated by [Equation 5](#):

$$R_1 = R_F \left[\frac{V_{HYST}}{V_{BATT}} \right] = 20 \text{ M}\Omega \left[\frac{50 \text{ mV}}{2.4 \text{ V}} \right] = 420 \text{ k}\Omega \tag{5}$$

4. Select a threshold voltage for V_{IN} rising (V_{THRS}) = 2.0 V.
5. Calculate R_2 as given by [Equation 6](#):

$$\begin{aligned} R_2 &= \frac{1}{\left[\left(\frac{V_{THRS}}{V_{BATT}} \right) - \frac{1}{R_1} - \frac{1}{R_1} \right]} \\ &= \frac{1}{\left[\left(\frac{2 \text{ V}}{1.2 \text{ V} \times 420 \text{ k}\Omega} \right) - \frac{1}{420 \text{ k}\Omega} - \frac{1}{20 \text{ M}\Omega} \right]} \\ &= 650 \text{ k}\Omega \end{aligned} \tag{6}$$

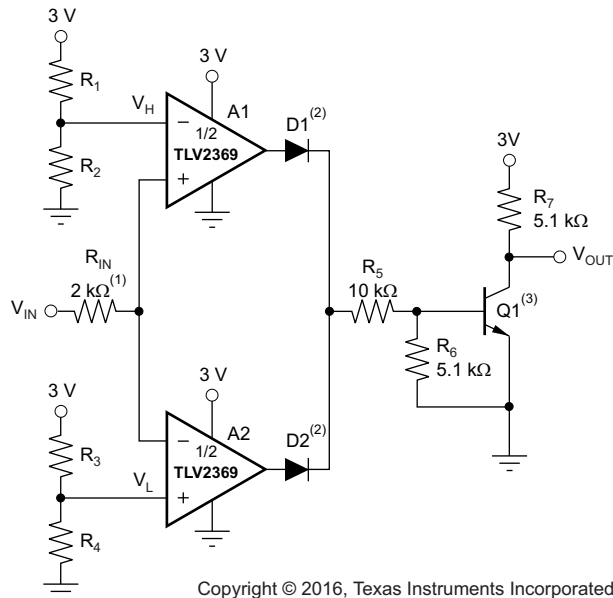
6. Calculate R_{BIAS} : The minimum supply voltage for this circuit is 1.8 V. The REF1112 has a current requirement of 1.2 μ A (max). Providing the REF1112 with 2 μ A of supply current assures proper operation. Therefore, R_{BIAS} is as given by [Equation 7](#).

$$R_{BIAS} = \frac{V_{BATTMIN}}{I_{BIAS}} = \frac{1.8 \text{ V}}{2 \mu\text{A}} = 0.9 \text{ M}\Omega \tag{7}$$

System Examples (continued)

8.3.2 Window Comparator

Figure 18 shows the TLV2369 used as a window comparator. The threshold limits are set by V_H and V_L , with V_H greater than V_L . When V_{IN} is less than V_H , the output of A1 is low. When V_{IN} is greater than V_L , the output of A2 is low. Therefore, both op amp outputs are at 0 V as long as V_{IN} is between V_H and V_L . This architecture results in no current flowing through either diode, Q1 is in cutoff, with the base voltage at 0 V, and V_{OUT} forced high.



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Figure 18. TLV2369 as a Window Comparator

If V_{IN} falls below V_L , the output of A2 is high, current flows through D2, and V_{OUT} is low. Likewise, if V_{IN} rises above V_H , the output of A1 is high, current flows through D1, and V_{OUT} is low. The window comparator threshold voltages are set as shown by Equation 8 and Equation 9:

$$V_H = \frac{R_2}{R_1 + R_2} \quad (8)$$

$$V_L = \frac{R_4}{R_3 + R_4} \quad (9)$$

9 Power Supply Recommendations

The TLV369 family is specified for operation from 1.8 V to 5.5 V (± 0.9 V to ± 2.75 V); many specifications apply from -40°C to $+125^\circ\text{C}$. The [Typical Characteristics](#) section presents parameters that can exhibit significant variance with regard to operating voltage or temperature.

CAUTION

Supply voltages larger than 7 V can permanently damage the device (see the [Absolute Maximum Ratings](#) table).

Place 0.1- μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies. For more detailed information on bypass capacitor placement; see the [Layout Guidelines](#) section.

10 Layout

10.1 Layout Guidelines

For best operational performance of the device, use good printed circuit board (PCB) layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole and the operational amplifier. Use bypass capacitors to reduce the coupled noise by providing low-impedance power sources local to the analog circuitry.
 - Connect low-ESR, 0.1- μ F ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of the circuitry is one of the simplest and most effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces electromagnetic interference (EMI) noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current. For more detailed information, see *Circuit Board Layout Techniques*, [SLOA089](#).
- To reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If these traces cannot be kept separate, crossing the sensitive trace perpendicularly is much better than crossing in parallel with the noisy trace.
- Place the external components as close to the device as possible. Keep R_F and R_G close to the inverting input in order to minimize parasitic capacitance, as shown in [Figure 19](#).
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.

10.2 Layout Example

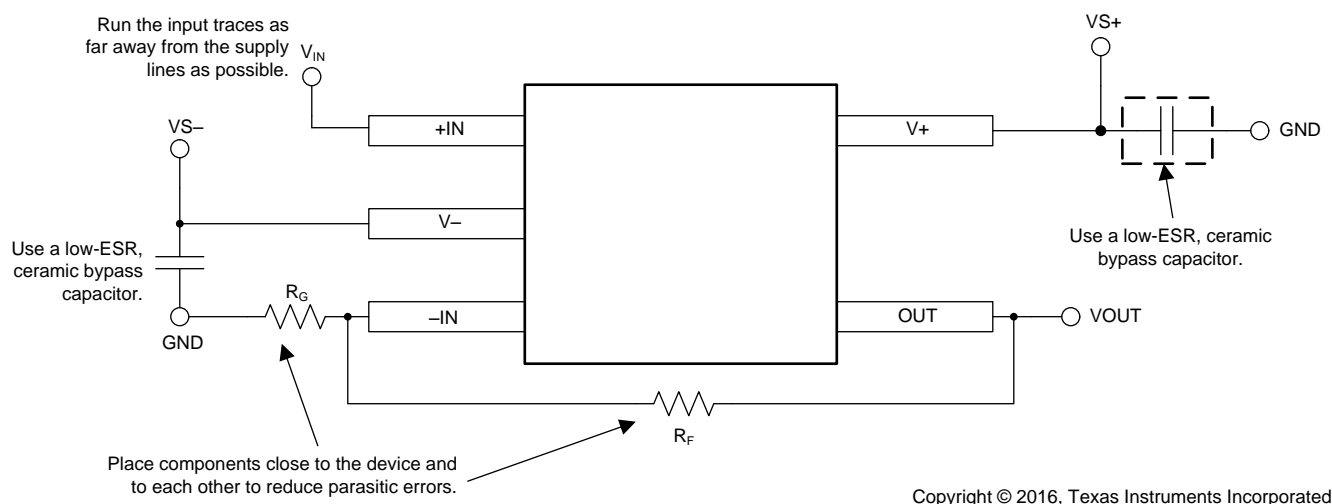
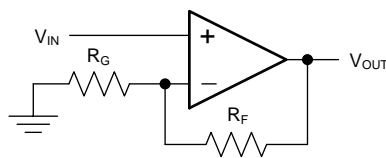


Figure 19. Operational Amplifier Board Layout for Noninverting Configuration



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Figure 20. Schematic Representation of [Figure 19](#)

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

The following documents are relevant to using the TLVx369, and are recommended for reference and available for download at www.ti.com, unless otherwise noted.

- REF1112 Data Sheet, [SBOS283](#)
- *Circuit Board Layout Techniques*, [SLOA089](#)
- *Handbook of Operational Amplifier Applications*, [SBOA092](#)
- *Analog Engineer's Pocket Reference*, [SLWY038](#)

11.1.1.1 Related Links

[Table 1](#) lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 1. Related Links

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|---------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| TLV369 | Click here | Click here | Click here | Click here | Click here |
| TLV2369 | Click here | Click here | Click here | Click here | Click here |

11.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.3 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| TLV2369IDGKR | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | 13JV | Samples |
| TLV2369IDGKT | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 125 | 13JV | Samples |
| TLV2369IDR | PREVIEW | SOIC | D | 8 | 2500 | TBD | Call TI | Call TI | -40 to 125 | | |
| TLV369IDCKR | ACTIVE | SC70 | DCK | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | 12K | Samples |
| TLV369IDCKT | ACTIVE | SC70 | DCK | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | 12K | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TLV2369IDGKR | VSSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| TLV2369IDGKT | VSSOP | DGK | 8 | 250 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| TLV369IDCKR | SC70 | DCK | 5 | 3000 | 178.0 | 9.0 | 2.4 | 2.5 | 1.2 | 4.0 | 8.0 | Q3 |
| TLV369IDCKT | SC70 | DCK | 5 | 250 | 178.0 | 9.0 | 2.4 | 2.5 | 1.2 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TLV2369IDGKR | VSSOP | DGK | 8 | 2500 | 366.0 | 364.0 | 50.0 |
| TLV2369IDGKT | VSSOP | DGK | 8 | 250 | 366.0 | 364.0 | 50.0 |
| TLV369IDCKR | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TLV369IDCKT | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



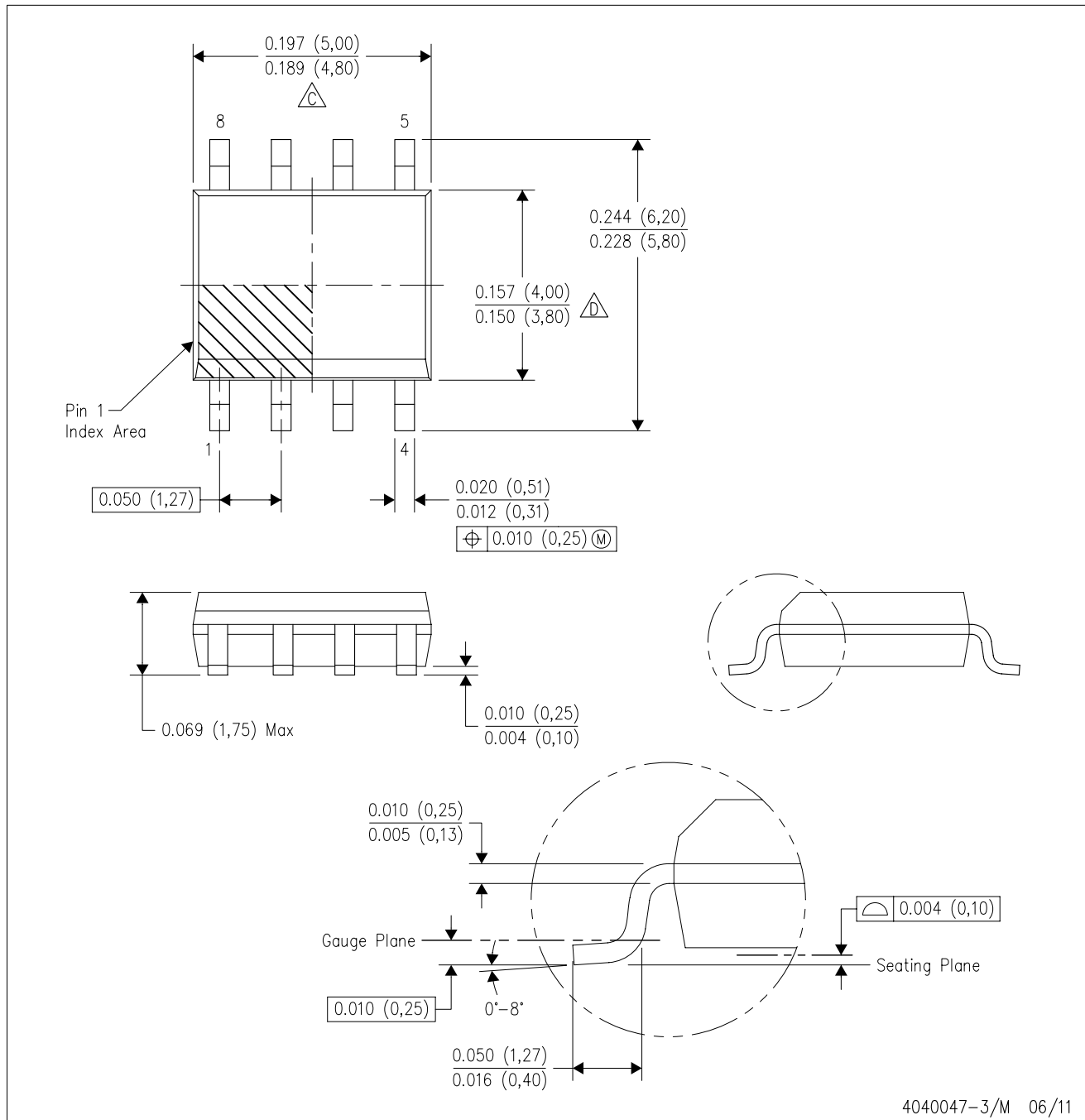
- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4040047-3/M 06/11

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